

ABSTRACT

After disposing metallic foils on either surface of a prepreg sheet of low compressibility having conducting holes filled with conductive paste, the prepreg sheet is compressed in a state of being kept at a relatively low temperature, and after
5 that, the temperature is raised under pressure to melt and harden the resin in the prepreg sheet, and thereby, the connecting resistance is stabilized, and a high-quality circuit board can be obtained.

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